

NCE P-Channel Enhancement Mode Power MOSFET

Description

The NCE2301 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

General Features

• $V_{DS} = -20V, I_{D} = -3A$

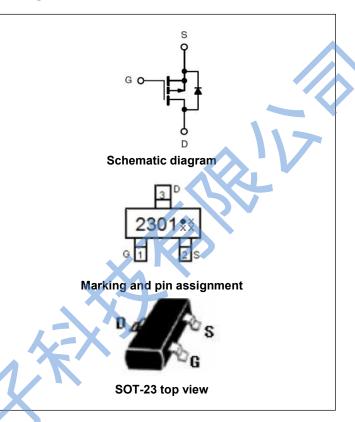
 $R_{DS(ON)} < 140 m\Omega$ @ V_{GS} =-2.5V

 $R_{DS(ON)}$ < 110m Ω @ V_{GS} =-4.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- PWM applications
- Load switch
- Power management



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2301*X	NCE2301	SOT-23	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _G s	±12	V
Drain Current-Continuous	I _D	-3	Α
Drain Current -Pulsed (Note 1)	I _{DM}	-10	Α
Maximum Power Dissipation	P _D	1	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance Junction-to-Ambient (Note 2)	Rosa	125	°C/W
Thermal Resistance, Junction-to-Ambient (1962)	RθJA	125	C/ VV

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V,V _{GS} =0V	-	-	-1	μA



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Parameter	Symbol	Condition	Min	Тур	Max	Unit
Gate-Body Leakage Current	Igss	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=-250\mu A$	-0.4	-0.7	-1	V
rain-Source On-State Resistance	В	V_{GS} =-4.5V, I_D =-3A	-	64	110	mΩ
Diani-Source Oil-State Resistance	R _{DS(ON)}	V_{GS} =-2.5 V , I_D =-2 A	-	89	140	mΩ
Forward Transconductance	g FS	V_{DS} =-5 V , I_{D} =-2 A	5	-	1	S
Gate resistance	R _G	F=1.0MHz	-	6.6	1	Ω
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ - 10\/\/ -0\/	-	841	ZI_	PF
Output Capacitance	Coss	V_{DS} =-10V, V_{GS} =0V, F=1.0MHz	-	75	5	PF
Reverse Transfer Capacitance	C _{rss}	r-1.0ivinz	1	47	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		IX	11	-	nS
Turn-on Rise Time	t _r	V _{DD} =-10V,I _D =-1A	-	35	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-4.5 V , R_{GEN} =10 Ω	-	30	-	nS
Turn-Off Fall Time	t _f	, - \ ' '	-	10	-	nS
Total Gate Charge	Qg	V = 40V1 = 24	-	7.4	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =-10V,I _D =-3A, V _{GS} =-4.5V	-	1	-	nC
Gate-Drain Charge	Q _{gd}	VGS4,5V	-	1.9	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =-3A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-3	Α

- **1.** Repetitive Rating: Pulse width limited by maximum junction temperature. **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

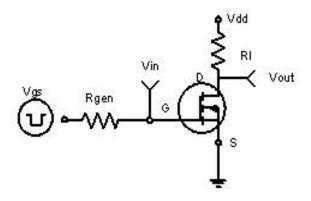


Figure 1:Switching Test Circuit

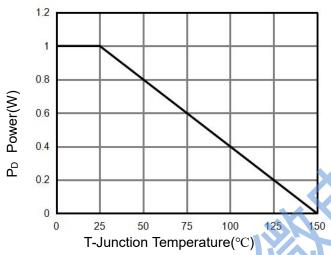


Figure 3 Power Dissipation

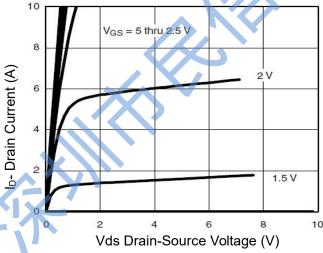


Figure 5 Output Characteristics

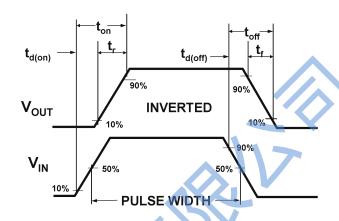


Figure 2:Switching Waveforms

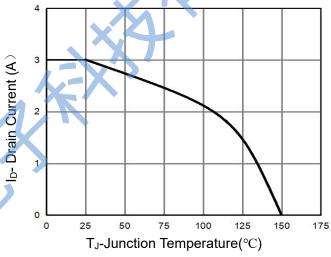


Figure 4 Drain Current

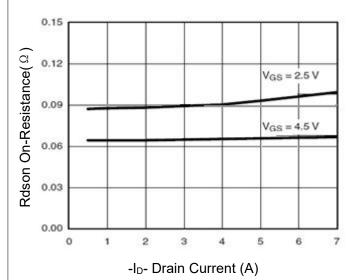
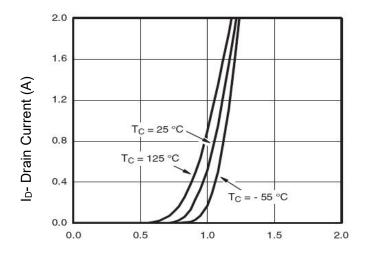
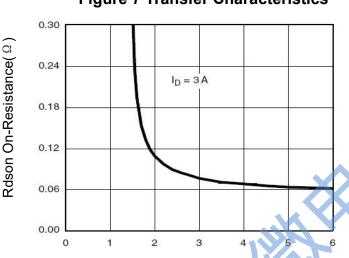


Figure 6 Drain-Source On-Resistance





Vgs Gate-Source Voltage (V)
Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs

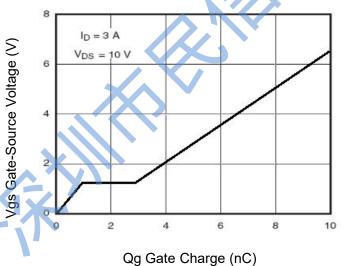
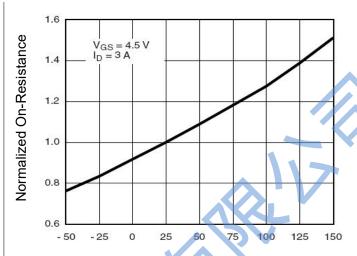
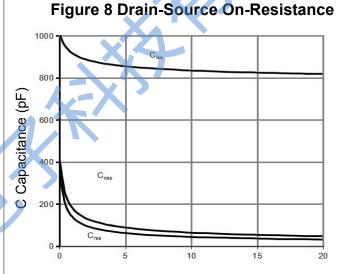


Figure 11 Gate Charge



T_J-Junction Temperature(°C)



Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds

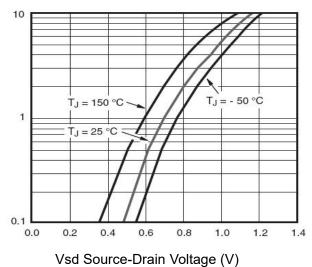
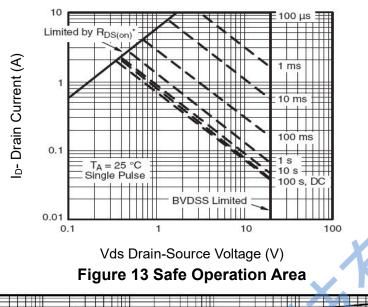


Figure 12 Source- Drain Diode Forward

Is- Reverse Drain Current (A)





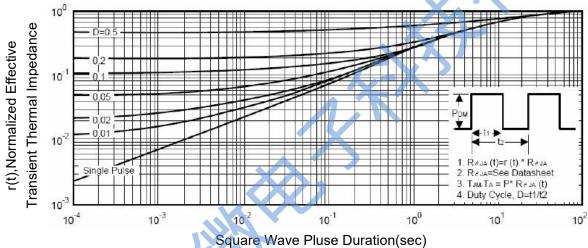
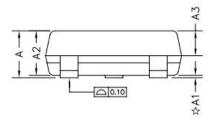
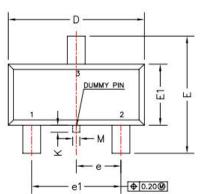


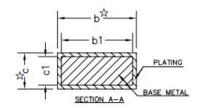
Figure 14 Normalized Maximum Transient Thermal Impedance

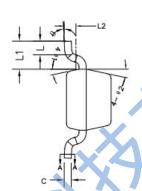


SOT-23 Package Information









Symbol	Millimeters			
Symbol	Min.	Max.		
Α	0.89	1.12		
A1	0.01	0.10		
A2	0.88	1.02		
A3	0.43	0.63		
b	0.36	0.50		
b1	0.35	0.45		
С	0.14	0.20		
c1	0.14	0.16		
D	2.80	3.00		
E	2.35	2.64		
E1	1.20	1.40		
е	0.90	1.00		
e1	1.80	2.00		
L	0.40	0.60		
L1	0.6REF			
L2	0.25BSC			
М	0.10	0.25		
K	0.00	0.25		
θ	0°	8°		
θ1	10°	14°		
θ2	10°	14°		



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